

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/15973	
1.3 Title of PCN	STM32WL3x - product enhancement	
1.4 Product Category	STM32WL33x, STM32WL31x and STM32WL30x.	
1.5 Issue date	2026-02-10	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	TSMC (Taiwan)

4. Description of change

	Old	New
4.1 Description	STM32WL3x (Revision B) product has limitations as described in STM32WL33xx device errata ES0612 - Version 7 (or below) - 07 Aug 2025	New STM32WL3x (Revision Z) product enhancement fixing: - Stepup convertor generates correct VLCD voltage on PB15 (only related to LCD application); feature only impacting STM32WL33x - Internal generated reference for comparator is independent from external Vbat variation (Vbat is the external power supply connected to Vdd) ; feature only impacting STM32WL33x New erratasheet release is : STM32WL33xx device errata ES0612 - Version 8 - February 2026
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	functionality enhancement	

5. Reason / motivation for change

5.1 Motivation	Improvements implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools. Die revision changes for from "B" to "Z" on Package Marking
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7. Timing / schedule

7.1 Date of qualification results	2026-04-24
7.2 Intended start of delivery	2026-06-06
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
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8.1 Description	15973 PCN15973 RER2427_STM32L33 - Die 4L0_Z cut2.4 - qual plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-02-10

9. Attachments (additional documentations)			
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15973 Public product.pdf 15973 PCN15973 RER2427_STM32L33 - Die 4L0_Z cut2.4 - qual plan.pdf 15973 _Additional information.pdf

10. Affected parts		
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10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32WL30K8V6	
	STM32WL30KBV6	
	STM32WL31C8V6	
	STM32WL31CBV6	
	STM32WL31KBV6	
	STM32WL33C8V6	
	STM32WL33C8V7	
	STM32WL33CBV6	
	STM32WL33CBV7	
	STM32WL33CCV6	
	STM32WL33CCV6A	
	STM32WL33CCV7	
	STM32WL33K8V6	
	STM32WL33K8V7	
	STM32WL33KBV6	
	STM32WL33KBV7	
	STM32WL33KCV6	
	STM32WL33KCV7	

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